



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China






## Thyristor/Diode and Thyristor/Thyristor, 135 A to 160 A (New INT-A-PAK Power Modules)



New INT-A-PAK

### FEATURES

- High voltage
- Electrically isolated by DBC ceramic ( $Al_2O_3$ )
- 3500  $V_{RMS}$  isolating voltage
- Industrial standard package
- High surge capability
- Glass passivated chips
- Modules uses high voltage power thyristor/diodes in three basic configurations
- Simple mounting
- UL approved file E78996 
- Designed and qualified for multiple level
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



RoHS  
COMPLIANT

PRODUCT SUMMARY	
$I_{T(AV)}$	135 A to 160 A
Type	Modules - Thyristor, Standard
Package	INT-A-PAK
Circuit	Two SCRs doubler circuit, SCR/diode doubler circuit, positive control, SCR/diode doubler circuit, negative control

### APPLICATIONS

- DC motor control and drives
- Battery charges
- Welders
- Power converters
- Lighting control
- Heat and temperature control

MAJOR RATINGS AND CHARACTERISTICS					
SYMBOL	CHARACTERISTICS	VSK.136..	VSK.142..	VSK.162..	UNITS
$I_{T(AV)}$	85 °C	135	140	160	A
$I_{T(RMS)}$		300	310	355	A
$I_{TSM}$	50 Hz	3200	4500	4870	
	60 Hz	3360	4712	5100	
$I^2t$	50 Hz	51.5	102	119	$kA^2s$
	60 Hz	47	92.5	108	
$I^2\sqrt{t}$		515.5	1013	1190	$kA^2\sqrt{s}$
$V_{RRM}$	Range	400 to 1600	400 to 1600	400 to 1600	V
$T_J$	Range	-40 to 125			°C

### ELECTRICAL SPECIFICATIONS

VOLTAGE RATINGS				
TYPE NUMBER	VOLTAGE CODE	$V_{RRM}/V_{DRM}$ , MAXIMUM REPETITIVE PEAK REVERSE VOLTAGE V	$V_{RSM}/V_{DSM}$ , MAXIMUM NON-REPETITIVE PEAK REVERSE VOLTAGE V	$I_{RRM}/I_{DRM}$ AT 125 °C mA
VS-VSK.136 VS-VSK.142 VS-VSK.162	04	400	500	50
	08	800	900	
	12	1200	1300	
	14	1400	1500	
	16	1600	1700	



ON-STATE CONDUCTION							
PARAMETER	SYMBOL	TEST CONDITIONS		VSK.136	VSK.142	VSK.162	UNITS
Maximum average on-state current at case temperature	$I_{T(AV)}$	180° conduction, half sine wave		135	140	160	A
				85	85	85	°C
Maximum RMS on-state current	$I_{T(RMS)}$	As AC switch		300	310	355	A
Maximum peak, one-cycle on-state, non-repetitive surge current	$I_{TSM}$	t = 10 ms	No voltage reappplied	3200	4500	4870	
		t = 8.3 ms	100 % $V_{RRM}$ reappplied	3360	4712	5100	
		t = 10 ms		Sine half wave, initial $T_J = T_J$ maximum	2700	3785	
		t = 8.3 ms	2800		3963	4300	
Maximum $I^2t$ for fusing	$I^2t$	t = 10 ms	No voltage reappplied	51.5	102	119	kA <sup>2</sup> s
		t = 8.3 ms	100 % $V_{RRM}$ reappplied	47	92.5	108	
		t = 10 ms		36.5	71.6	84	
		t = 8.3 ms	33.3	65.4	76.7		
Maximum $I^2\sqrt{t}$ for fusing	$I^2\sqrt{t}$	t = 0.1 ms to 10 ms, no voltage reappplied		515.5	1013	1190	kA <sup>2</sup> √s
Low level value of threshold voltage	$V_{T(TO)1}$	$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)})$ , $T_J$ maximum		0.86	0.83	0.8	V
High level value of threshold voltage	$V_{T(TO)2}$	$(I > \pi \times I_{T(AV)})$ , $T_J$ maximum		1.05	1	0.98	
Low level value on-state slope resistance	$r_{t1}$	$(16.7\% \times \pi \times I_{T(AV)} < I < \pi \times I_{T(AV)})$ , $T_J$ maximum		2.02	1.78	1.67	mΩ
High level value on-state slope resistance	$r_{t2}$	$(I > \pi \times I_{T(AV)})$ , $T_J$ maximum		1.65	1.43	1.38	
Maximum on-state voltage drop	$V_{TM}$	$I_{TM} = \pi \times I_{T(AV)}$ , $T_J = 25\text{ °C}$ , 180° conduction		1.57	1.55	1.54	V
Maximum forward voltage drop	$V_{FM}$	$I_{TM} = \pi \times I_{T(AV)}$ , $T_J = 25\text{ °C}$ , 180° conduction		1.57	1.55	1.54	V
Maximum holding current	$I_H$	Anode supply = 6 V initial $I_T = 30\text{ A}$ , $T_J = 25\text{ °C}$		200			mA
Maximum latching current	$I_L$	Anode supply = 6 V resistive load = 1 Ω Gate pulse: 10 V, 100 μs, $T_J = 25\text{ °C}$		400			

SWITCHING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Typical delay time	$t_{gd}$	$T_J = 25\text{ °C}$	Gate current = 1 A, $di_g/dt = 1\text{ A}/\mu\text{s}$ $V_d = 0.67\% V_{DRM}$	1	μs
Typical rise time	$t_{gr}$			2	
Typical turn-off time	$t_q$	$I_{TM} = 300\text{ A}$ , - $di/dt = 15\text{ A}/\mu\text{s}$ ; $T_J = T_J$ maximum $V_R = 50\text{ V}$ ; $dV/dt = 20\text{ V}/\mu\text{s}$ ; gate 0 V, 100 Ω		50 to 200	

BLOCKING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak reverse and off-state leakage current	$I_{RRM}$ , $I_{DRM}$	$T_J = 125\text{ °C}$		50	mA
RMS insulation voltage	$V_{INS}$	50 Hz, circuit to base, all terminals shorted, t = 1 s		3500	V
Critical rate of rise of off-state voltage	dV/dt	$T_J = T_J$ maximum, exponential to 67 % rated $V_{DRM}$		1000	V/μs



TRIGGERING					
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES	UNITS
Maximum peak gate power	$P_{GM}$	$t_p \leq 5 \text{ ms}$ , $T_J = T_J \text{ maximum}$		12	W
Maximum average gate power	$P_{G(AV)}$	$f = 50 \text{ Hz}$ , $T_J = T_J \text{ maximum}$		3	
Maximum peak gate current	$I_{GM}$	$t_p \leq 5 \text{ ms}$ , $T_J = T_J \text{ maximum}$		3	A
Maximum peak negative gate voltage	$-V_{GT}$			10	V
Maximum required DC gate voltage to trigger	$V_{GT}$	$T_J = -40 \text{ }^\circ\text{C}$	Anode supply = 6 V, resistive load; $R_a = 1 \text{ } \Omega$	4	
		$T_J = 25 \text{ }^\circ\text{C}$		2.5	
		$T_J = T_J \text{ maximum}$		1.7	
Maximum required DC gate current to trigger	$I_{GT}$	$T_J = -40 \text{ }^\circ\text{C}$		270	mA
		$T_J = 25 \text{ }^\circ\text{C}$		150	
		$T_J = T_J \text{ maximum}$		80	
Maximum gate voltage that will not trigger	$V_{GD}$	$T_J = T_J \text{ maximum}$ , rated $V_{DRM}$ applied		0.3	V
Maximum gate current that will not trigger	$I_{GD}$			10	mA
Maximum rate of rise of turned-on current	$di/dt$	$T_J = T_J \text{ maximum}$ , $I_{TM} = 400 \text{ A}$ rated $V_{DRM}$ applied		300	A/ $\mu\text{s}$

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	VSK.136	VSK.142	VSK.162	UNITS
Maximum junction operating temperature range	$T_J$		-40 to 125			$^\circ\text{C}$
Maximum storage temperature range	$T_{Stg}$		-40 to 150			
Maximum thermal resistance, junction to case per junction	$R_{thJC}$	DC operation	0.18	0.18	0.16	K/W
Maximum thermal resistance, case to heatsink per module	$R_{thCS}$	Mounting surface, smooth, flat and greased	0.05			
Mounting torque $\pm 10 \%$		IAP to heatsink busbar to IAP	A mounting compound is recommended and the torque should be rechecked after a period of 3 hours to allow for the spread of the compound. Lubricated threads.			Nm
Approximate weight						4 to 6
			200			g
			7.1			oz.
Case style			INT-A-PAK			

$\Delta R$ CONDUCTION PER JUNCTION											
DEVICES	SINUSOIDAL CONDUCTION AT $T_J$ MAXIMUM					RECTANGULAR CONDUCTION AT $T_J$ MAXIMUM					UNITS
	180°	120°	90°	60°	30°	180°	120°	90°	60°	30°	
VSK.136	0.007	0.01	0.013	0.0155	0.017	0.009	0.012	0.014	0.015	0.017	K/W
VSK.142	0.0019	0.0019	0.0020	0.0020	0.0021	0.0018	0.0022	0.0023	0.0023	0.0020	
VSK.162	0.0030	0.0031	0.0032	0.0033	0.0034	0.0029	0.0036	0.0039	0.0041	0.0040	

**Note**

- Table shows the increment of thermal resistance  $R_{thJC}$  when devices operate at different conduction angles than DC

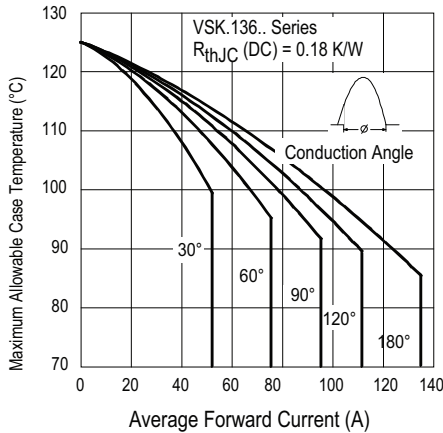


Fig. 1 - Current Ratings Characteristics

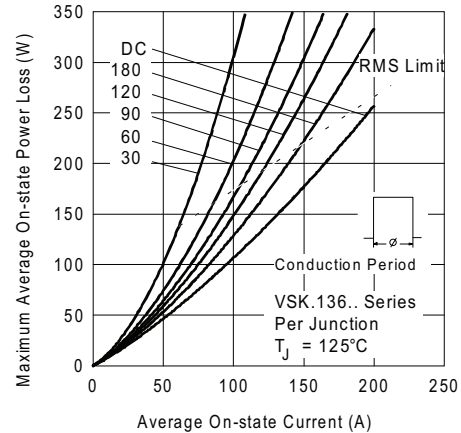


Fig. 4 - On-State Power Loss Characteristics

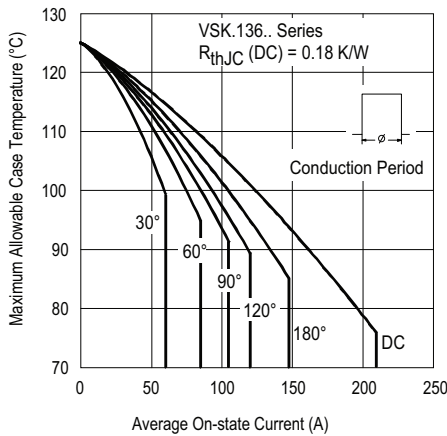


Fig. 2 - Current Ratings Characteristics

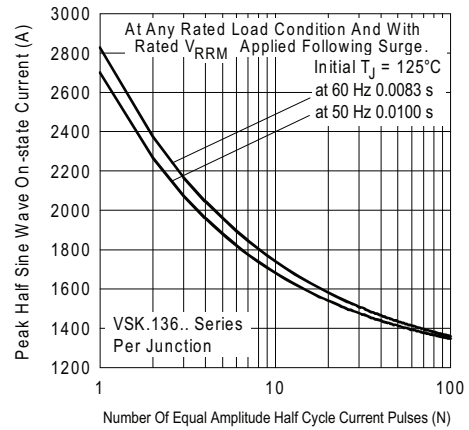


Fig. 5 - Maximum Non-Repetitive Surge Current

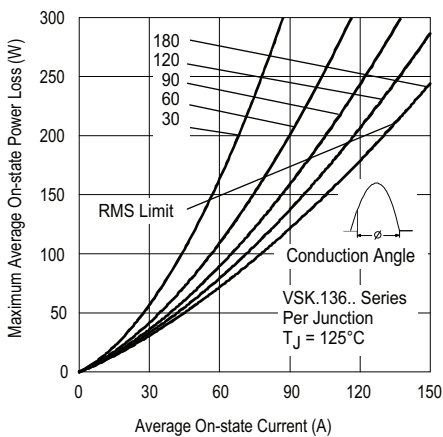


Fig. 3 - On-State Power Loss Characteristics

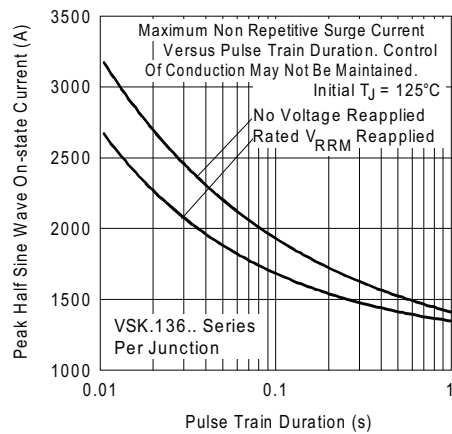


Fig. 6 - Maximum Non-Repetitive Surge Current

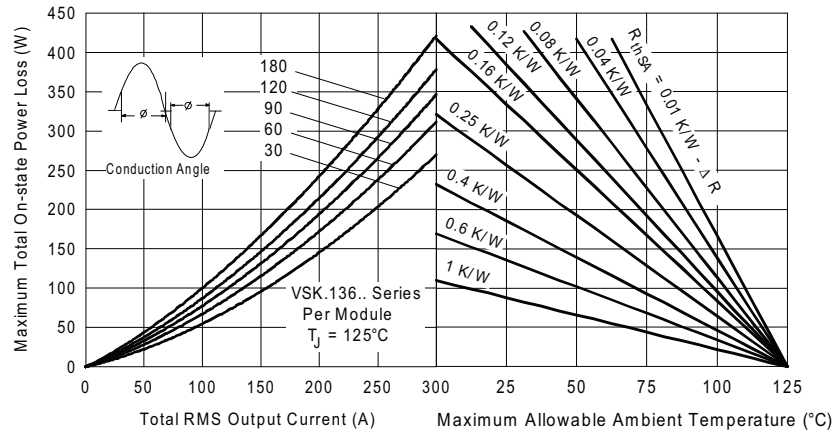


Fig. 7 - On-State Power Loss Characteristics

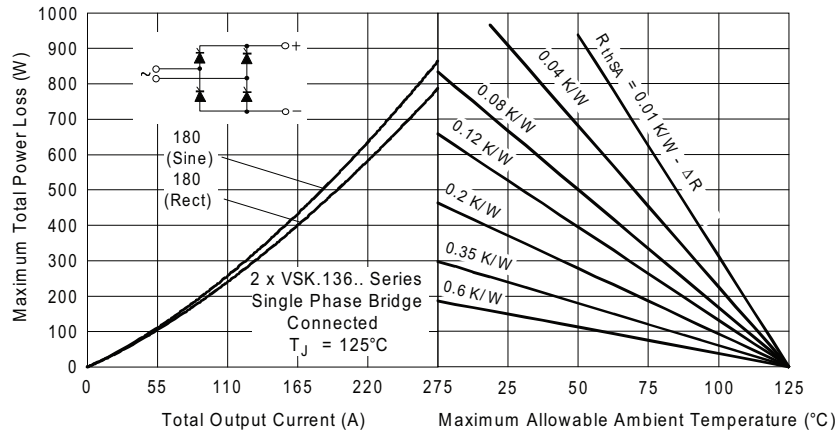


Fig. 8 - On-State Power Loss Characteristics

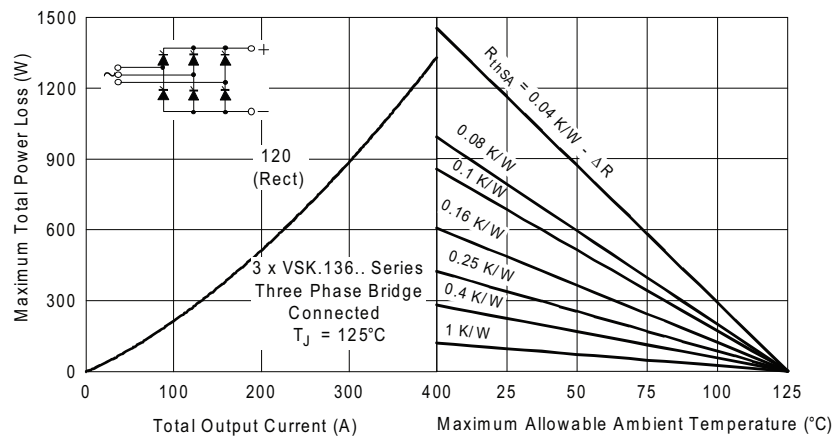


Fig. 9 - On-State Power Loss Characteristics

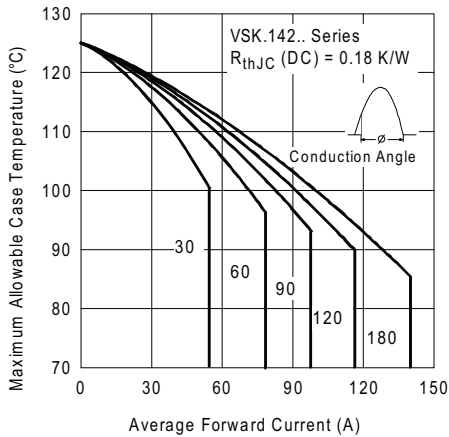


Fig. 10 - Current Ratings Characteristics

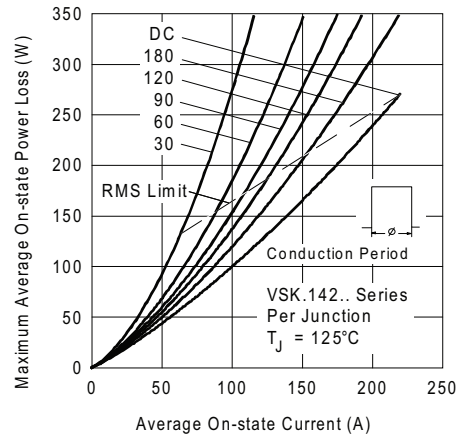


Fig. 13 - On-State Power Loss Characteristics

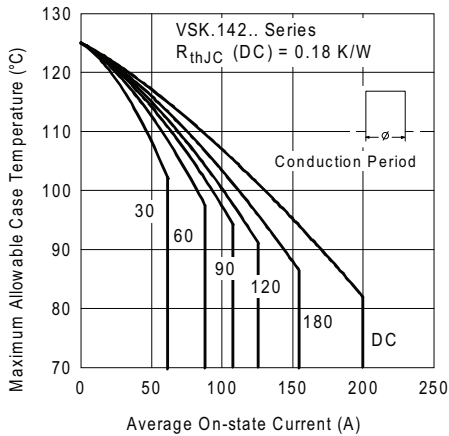


Fig. 11 - Current Ratings Characteristics

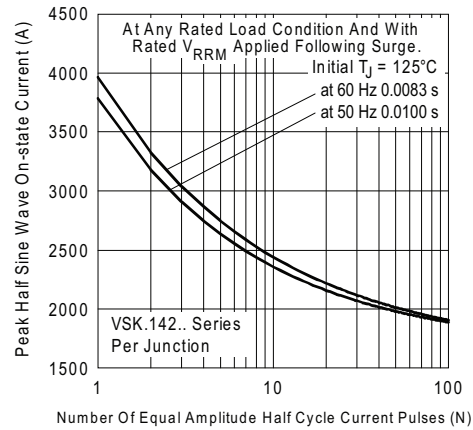


Fig. 14 - Maximum Non-Repetitive Surge Current

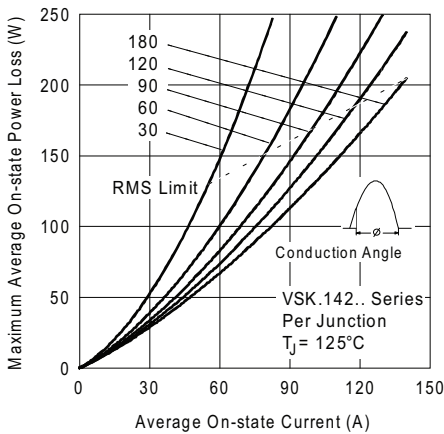


Fig. 12 - On-State Power Loss Characteristics

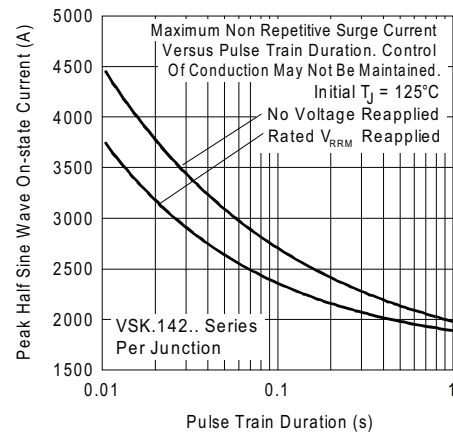


Fig. 15 - Maximum Non-Repetitive Surge Current

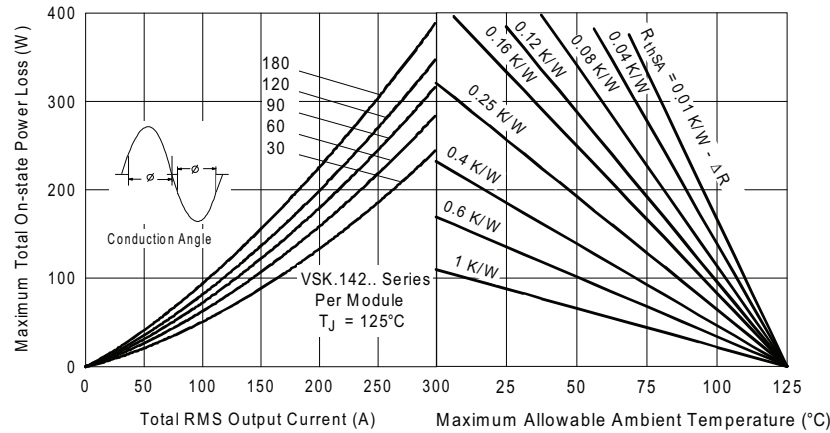


Fig. 16 - On-State Power Loss Characteristics

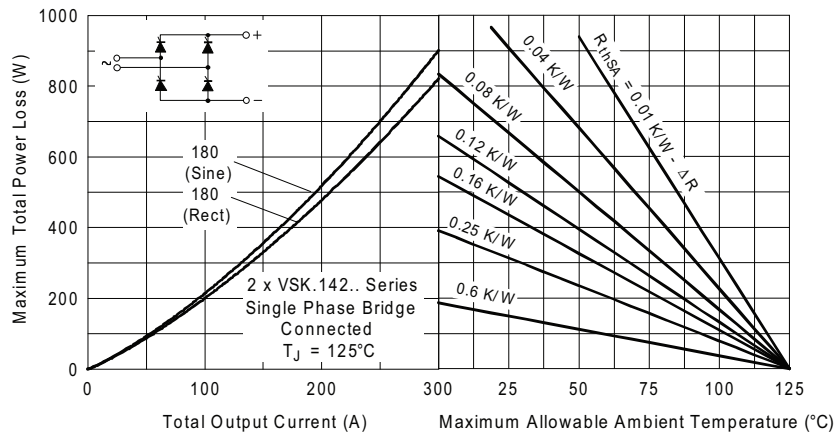


Fig. 17 - On-State Power Loss Characteristics

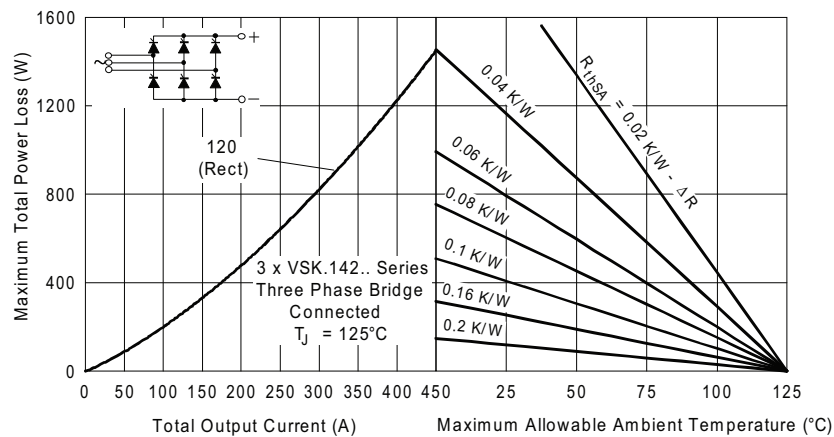


Fig. 18 - On-State Power Loss Characteristics



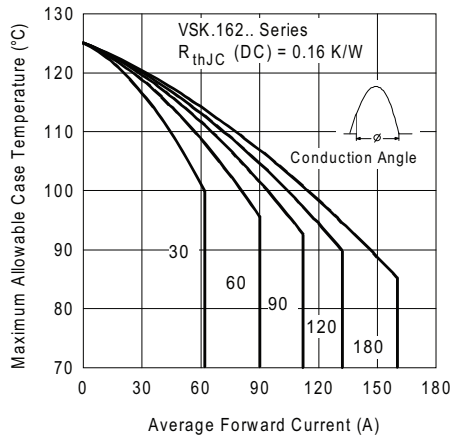


Fig. 19 - Current Ratings Characteristics

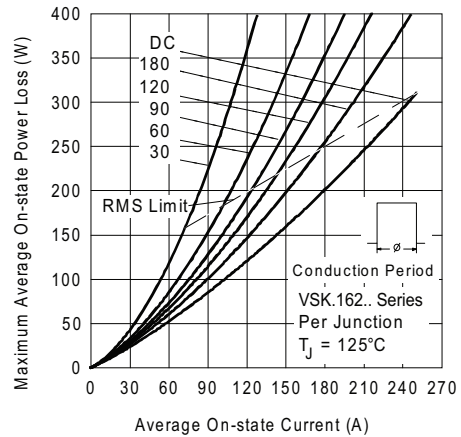


Fig. 22 - On-State Power Loss Characteristics

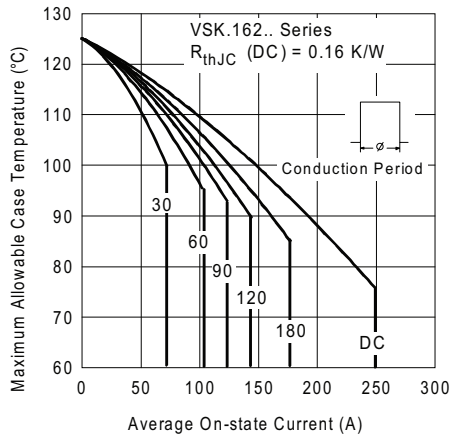


Fig. 20 - Current Ratings Characteristics

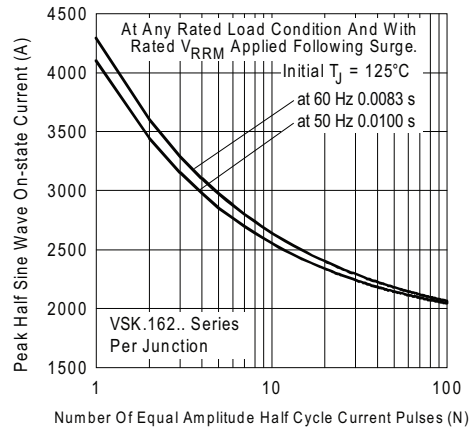


Fig. 23 - Maximum Non-Repetitive Surge Current

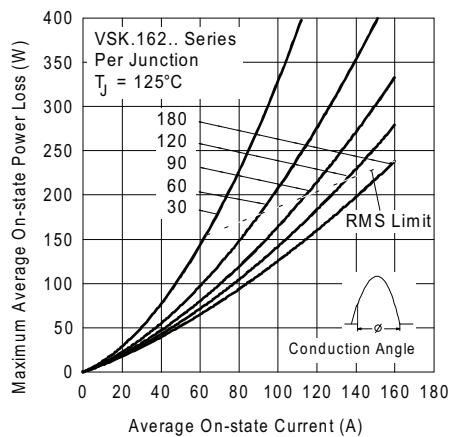


Fig. 21 - On-State Power Loss Characteristics

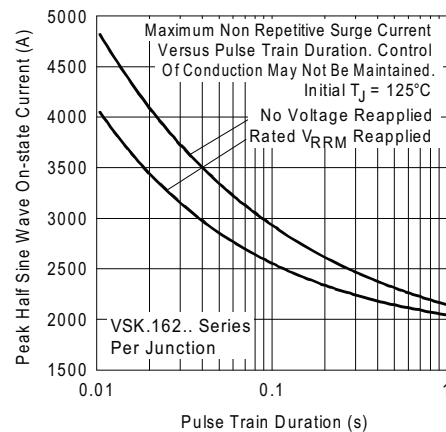


Fig. 24 - Maximum Non-Repetitive Surge Current

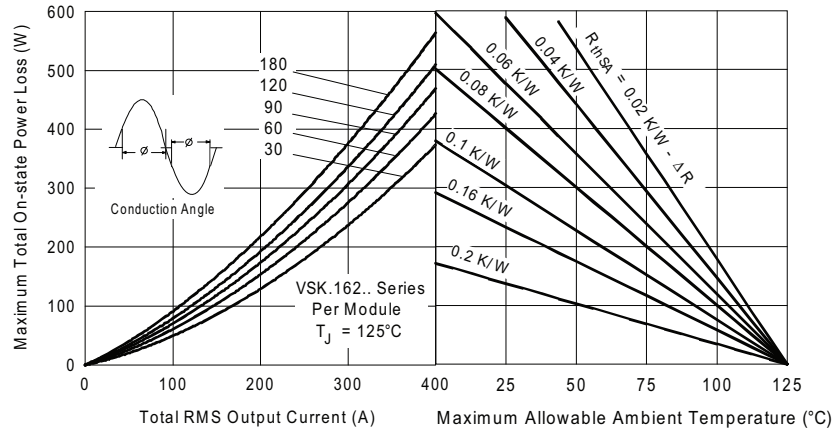


Fig. 25 - On-State Power Loss Characteristics

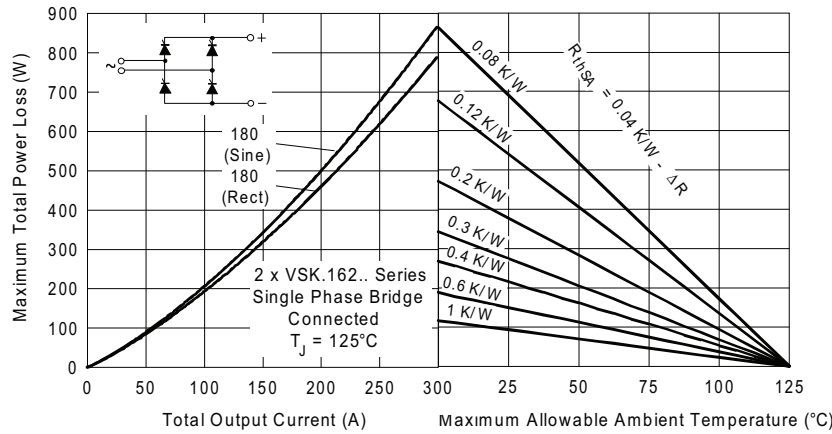


Fig. 26 - On-State Power Loss Characteristics

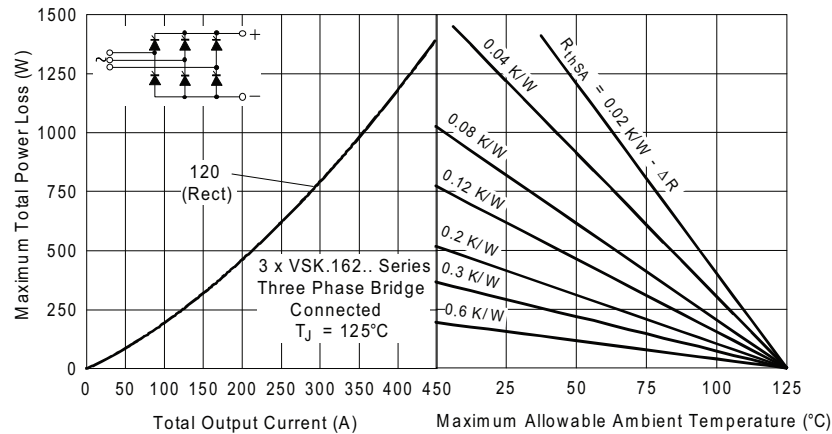


Fig. 27 - On-State Power Loss Characteristics

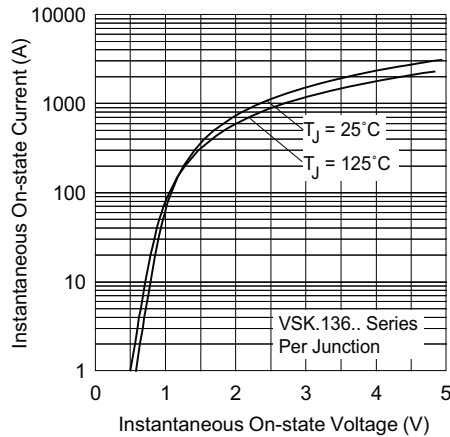


Fig. 28 - On-State Voltage Drop Characteristics

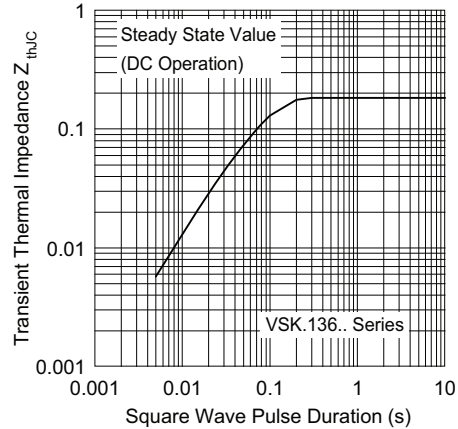


Fig. 31 - Thermal Impedance  $Z_{thJC}$  Characteristics

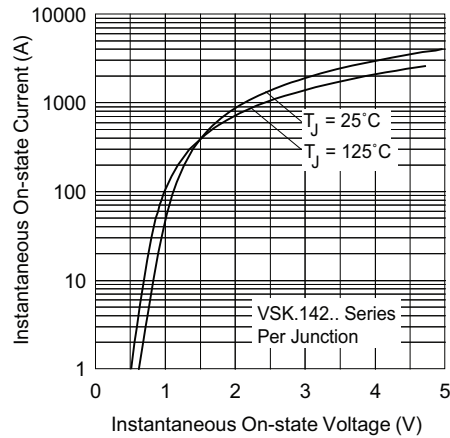


Fig. 29 - On-State Voltage Drop Characteristics

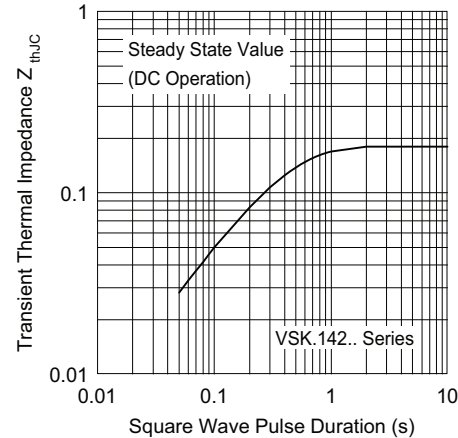


Fig. 32 - Thermal Impedance  $Z_{thJC}$  Characteristics

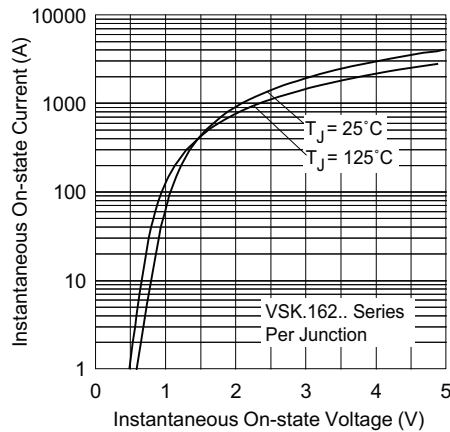


Fig. 30 - On-State Voltage Drop Characteristics

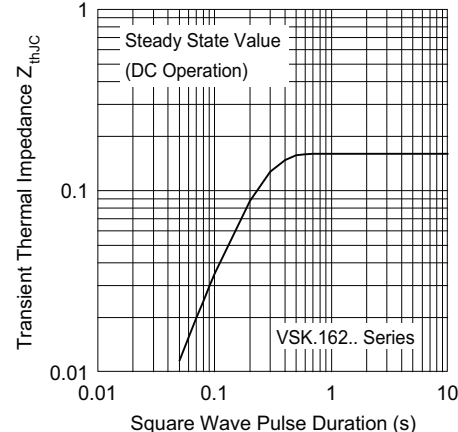


Fig. 33 - Thermal Impedance  $Z_{thJC}$  Characteristics

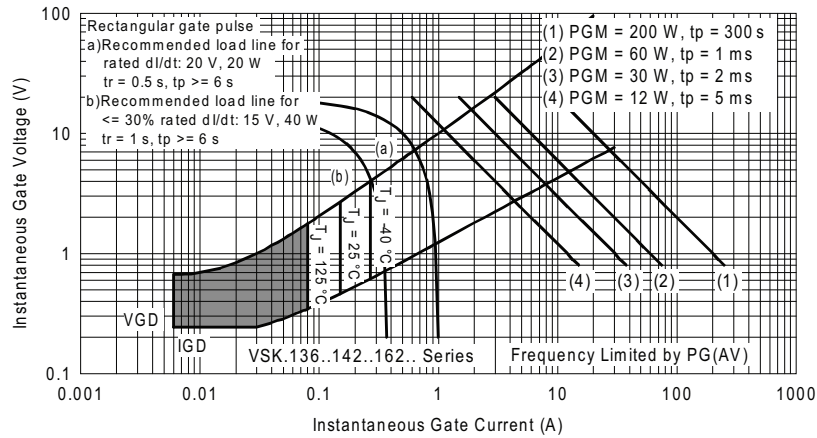


Fig. 34 - Gate Characteristics

**ORDERING INFORMATION TABLE**

Device code	<b>VS-VS</b>	<b>KT</b>	<b>162</b>	<b>16</b>	<b>PbF</b>
	①	②	③	④	⑤
	<b>1</b>	-	Vishay Semiconductors product		
	<b>2</b>	-	Circuit configuration		
	<b>3</b>	-	Current rating: $I_{T(AV)}$		
	<b>4</b>	-	Voltage code x 100 = $V_{RRM}$		
	<b>5</b>	-	PbF = Lead (Pb)-free		

**Note**

- To order the optional hardware go to [www.vishay.com/doc?95172](http://www.vishay.com/doc?95172)

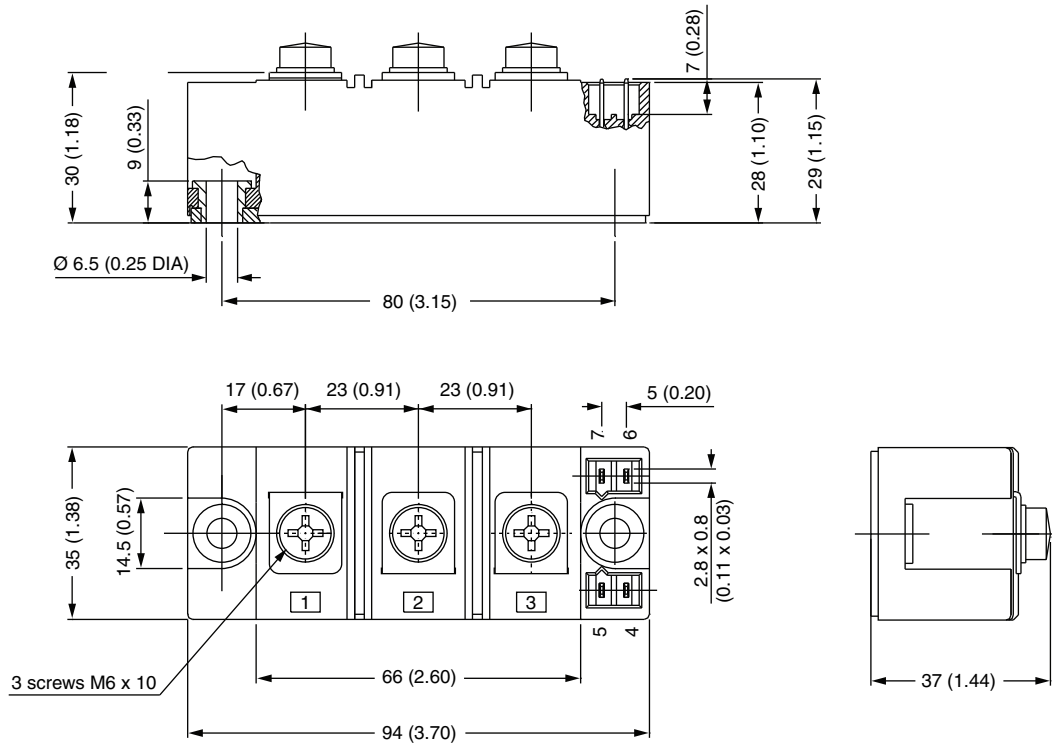


CIRCUIT CONFIGURATION		
CIRCUIT DESCRIPTION	CIRCUIT CONFIGURATION CODE	CIRCUIT DRAWING
Two SCRs doubler circuit	T	
SCR/diode doubler circuit, positive control	H	
SCR/diode doubler circuit, negative control	L	

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?95067">www.vishay.com/doc?95067</a>

## INT-A-PAK IGBT/Thyristor

**DIMENSIONS** in millimeters (inches)





## **Disclaimer**

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.